TOSHIBA Photo-Interrupter Infrared LED+Phototransistor

TLP801A

Optical Switches

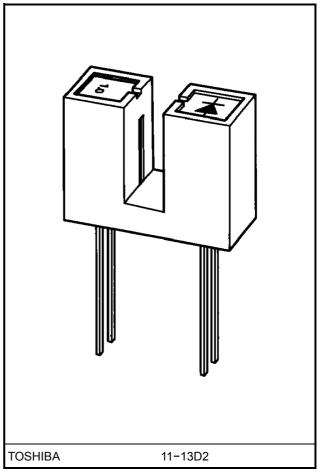
Position And Rotation Detection

Position Detection In FDDS(Floppy Disk Drives)

Timing Detection In Copiers, Printers, Fax Machines, Etc.

The TLP801A photo-interrupter can be used for high-speed position detection.

- Gap: 3mm
- Resolution: Slit width = 1mm
- Fast response speed: t_r , $t_f = 6\mu s(typ.)$
- High current transfer ratio: $I_C / I_F = 10\%$ (min)
- Designed for direct mounting on printed circuit boards
- Package material: Polycarbonate



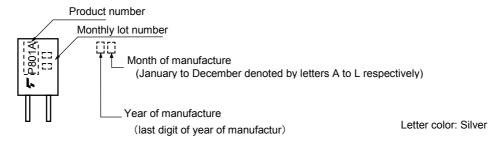
Weight: 0.78g(typ.)

Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit			
LED	Forward current	I _F	50	mA			
	Forward current derating (Ta > 25°C)	ΔI _F / °C	-0.33	mA / °C			
	Reverse voltage	V _R	5	V			
Detector	Collector-emitter voltage	V _{CEO}	30	V			
	Emittercollector voltage	V _{ECO}	5	٧			
	Collector power dissipation	PC	75	mW			
	Collector power dissipation derating(Ta > 25°C)	ΔP _C / °C	-1	mW / °C			
	Collector current	I _C	50	mA			
Operating temperature range		T _{opr}	-25~85	°C			
Storage temperature range		T _{stg}	-40~100	°C			

2002-09-25

Markings



Optical And Electrical Characteristics(Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
LED	Forward voltage	V _F	I _F = 10mA	1.00	1.15	1.30	V
	Reverse current	I _R	V _R = 5V	_	_	10	μA
	Peak emission wavelength	λP	I _F = 20mA	_	940	1	nm
Detector	Dark current	I _D (I _{CEO})	V _{CE} = 24V, I _F = 0	_	-	0.1	μΑ
	Peak sensitivity wavelength	λ _P		_	820	_	nm
Coupled	Current transfer ratio	I _C / I _F	V _{CE} = 5V, I _F = 20mA	10	_	165	%
	Collector–emitter saturation voltage	V _{CE(sat)}	I _F = 20mA, I _C = 1mA	_	0.15	0.4	V
	Rise time	t _r	V _{CC} = 5V, I _C = 2mA,	_	6	_	116
	Fall time	t _f	$R_L = 100\Omega$	_	6		μs

2

Precautions

The following points must be borne in mind.

- Soldering temperature: 260°C max
 Soldering time: 5s max
 (Soldering must be performed 1.5mm under the package body.)
- 2. Clean only the soldered part of the leads. Do not immerse the entire package in the cleaning solvent.
- 3. Mount the device on a level surface.
- 4. Screws should be tightened to a clamping torque of 0.59 N⋅m.
- 5. The package is made of polycarbonate. Polycarbonate is usually stable with acid, alcohol and aliphatic hydrocarbons, however, with petrochemicals (such as benzene, toluene and acetone), alkalis, aromatic hydrocarbons, or chloric hydrocarbons, polycarbonate may crack, swell or melt.

Please take this into account when chosing a packaging material by referring to the table below.

<Chemicals Which Should Not Be Used With Polycarbonate>

	Phenomenon	Chemicals	
Α	Staining and slight deterioration	Nitric acid (diluted), hydrogen peroxide, chlorine	
В	Cracking, crazed or swelling	Acetic acid (70% or more) Gasoline Methyl ethyl ketone, ethyl acetate, butyl acetate Ethyl methacrylate, ethyl ether, MEK Acetone, m-amino alcohol, carbon tetrachloride Carbon disulfide, trichloroethylene, cresol Thinners,oil of turpentine Triethanolamine, TCP, TBP	
С	Melting (): Used as solvent	Concentrated sulfuric acid Benzene Styrene, acrylonitrile, vinyl acetate Ethylenediamine, diethylenediamine (Chloroform, methyl chloride, tetrachloromethane,dioxane, 1, 2–dichloroethane)	
D	Decomposition	Ammonia water Other alkalis	

6. Conversion efficiency falls over time due to current which flows in the infrared LED.

When designing a circuit, take into account this change in conversion efficiency over time.

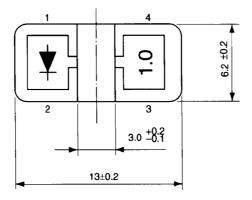
The ratio of fluctuation in conversion efficiency to fluctuation in infrared LED optical output is 1:1.

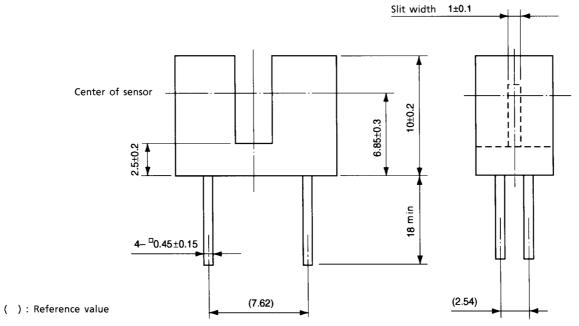
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$$\frac{I_{C} / I_{F} (t)}{I_{C} / I_{F} (0)} = \frac{P_{O} (t)}{P_{O} (0)}$$

Package Dimensions

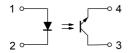
11-13D2 Unit: mm



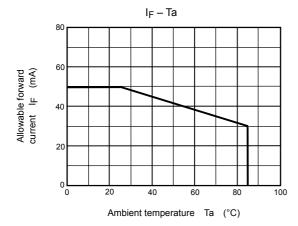


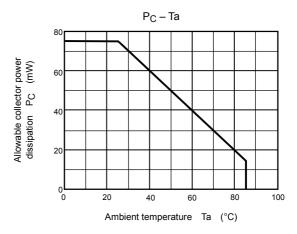
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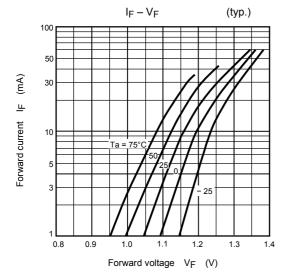
Pin Connection

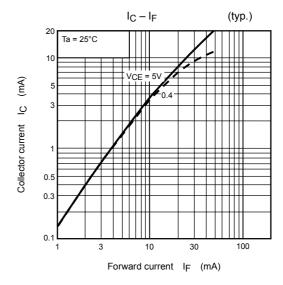


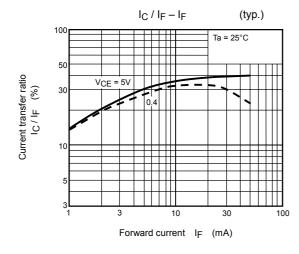
- 1. Anode
- 2. Cathode
- 3. Collector
- 4. Emitter

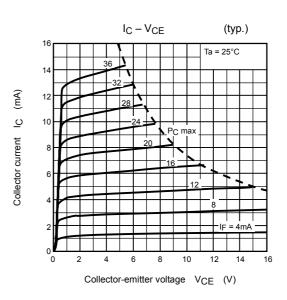




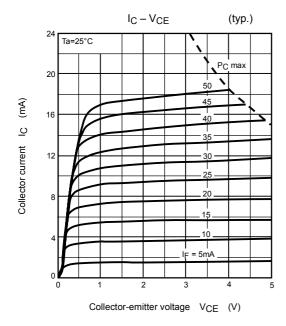


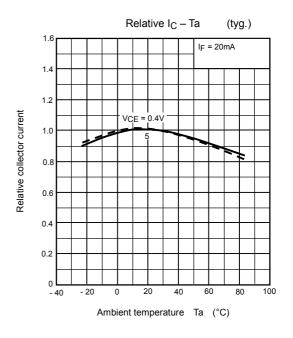


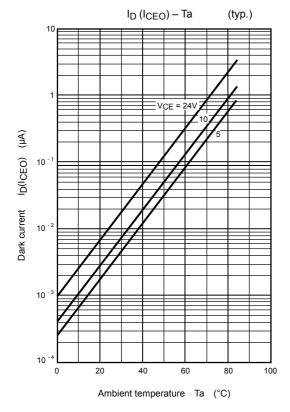


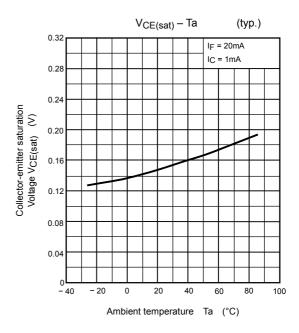


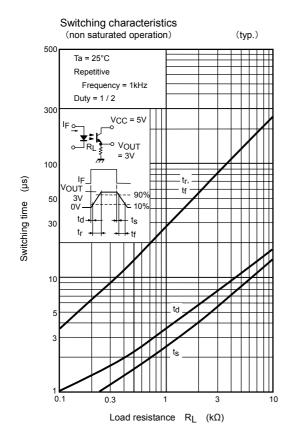
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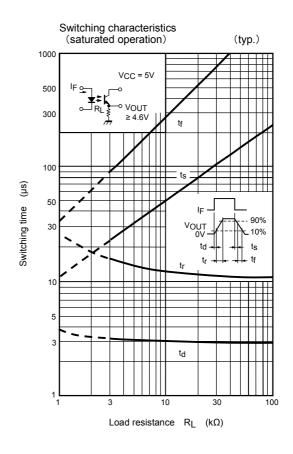


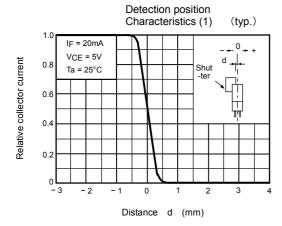


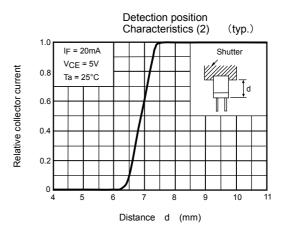






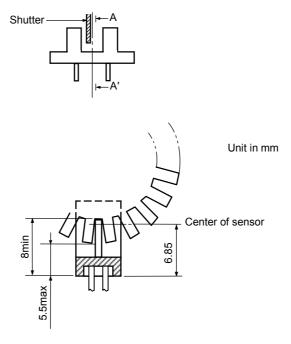






Relative Positioning Of Shutter And Device

For normal operation position the shutter and the device as shown in the figure below. By considering the device's detection direction characteristic and switching time, determine the shutter slit width and pitch.



Cross section between A and A'

8 2002-09-25

RESTRICTIONS ON PRODUCT USE

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